

GT0108 8-Bit Bidirectional Voltage-Level Translator

1 Features	2 Application
- No direction-control - Data rates 24 Mbps (Push Pull) 2 Mbps (Open Drain) - 1.65 V to 3.6 V on A port and 2.3 V to 5.5 V on B	- Handset/Smartphone - MART - IPC - GPIO
port (V _{CCA} ≤ V _{CCB}) - V _{CC} isolation feature: If either V _{CC} input is at GND, both ports are in the high-impedance state - No power-supply sequencing required: either V _{CCA} or V _{CCB} can be ramped first - I _{off} supports partial-power-down mode operation - Operating temperature range:-40°C to +85°C	

3 Description **Circuit Diagram** This 8-bit non-inverting translator which is a bidirectional voltagelevel translator and can be used to build digital switching compatibility between multi voltage systems. This IC uses two separate configurable power supply tracks that including A ports supporting operating voltages from 1.65 V to 3.6 V with tracking V_{CCA} supply, and also including B ports supporting operating voltages from 2.3 V to 5.5 V with tracking V_{CCB} supply. The advantage above provides the support of both lower and higher logic signal levels while providing bidirectional translation capabilities between any of the 1.8-V, 2.5-V, 3.3-V, and 5- V Micro voltage circuit points. **Processors** Placing output-enable (OE) input to low level, all I/Os are forced to high-impedance state that significantly lower the quiescent current consumption. In order to ensure the high-impedance state during power up or power down, OE pin should be tied to GND via a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.



4 Revision History

Revision	Date	Note
Rev. A1. 0	2023. 09. 21	Original Version
Rev. A1. 1	2023. 09. 09	Additional Switch Characteristics Data
Rev. A1. 2	2023. 10. 24	1.Updated Package Qty 2.Added Tape and Reel Information
Rev. A1. 3	2023. 12. 18	Updated New Package BQG
Rev. A1. 4	2024. 01. 26	Updated Part Name

The latest datasheet version should be checked on the GTIC official website, as the company does not actively inform customers about updates to the datasheet.

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5 Device Summary, Pin and Packages

Table 5-1. Device Summary(1)

Serial Name	Part Name	Package	Body Size (Nom)	Marking ⁽²⁾	MSL ⁽³⁾	Package Qty
	GT0108TG	TSSOP20	6.50mm×4.40mm	GT0108 XXXXXXX	3	Tape and Reel,4000
GT0108	GT0108BQG	QFN3×3-20L	3.00mm×3.00mm	GT0108B XXXXX	3	Tape and Reel,5000
	GT0108QG	QFN3×3-20L	3.00mm×3.00mm	GT0108 XXXXX	3	Tape and Reel,5000

⁽¹⁾For all available packages, please contact product sales.

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⁽²⁾There may be additional marking, which relates to the lot trace code information (data code and Vendor code), the logo or the environmental category on the device.

⁽³⁾MSL, The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications.

^{(4)&}quot;XXXXX" in Marking will be appeared as the batch code.



5 Device Summary, Pin and Packages (Continued)

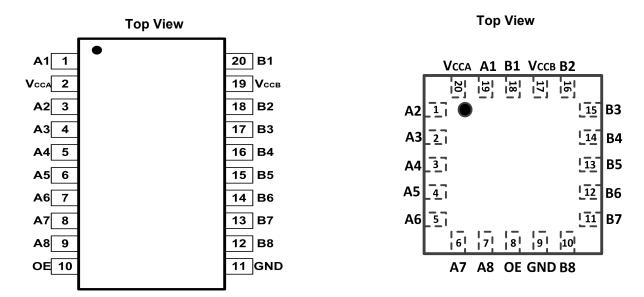


Fig.5-1. GT0108: TG (TSSOP20) Package

Fig.5-2. GT0108: BQG (QFN3×3-20L) Package

Top View

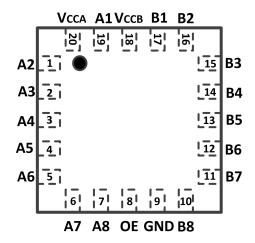


Fig.5-3. GT0108: QG (QFN3×3-20L) Package

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5 Device Summary, Pin and Packages(Continued)

Table 5-2. Pin Definition

Pin I/O Eunation					Franction
Name	TG	BQG	QG	I/O	Function
A1	1	19	19	I/O	Input/Output 1. Referenced to Vcca.
Vcca	2	20	20	-	A-Port power supply.
A2	3	1	1	I/O	Input/Output 2. Referenced to Vcca.
A3	4	2	2	I/O	Input/Output 3. Referenced to Vcca.
A4	5	3	3	I/O	Input/Output 4. Referenced to Vcca.
A5	6	4	4	I/O	Input/Output 5. Referenced to Vcca.
A6	7	5	5	I/O	Input/Output 6. Referenced to Vcca.
A7	8	6	6	I/O	Input/Output 7. Referenced to Vcca.
A8	9	7	7	I/O	Input/Output 8. Referenced to Vcca.
OE	10	8	8		Tri-state output mode. Pull low put all outputs in
OL .	10	0	0	1	tri-state. Referenced to V _{CCA}
GND	11	9	9	-	Ground
B8	12	10	10	I/O	Input/Output 8. Referenced to V _{CCB}
B7	13	11	11	I/O	Input/Output 7. Referenced to V _{CCB}
B6	14	12	12	I/O	Input/Output 6. Referenced to V _{CCB}
B5	15	13	13	I/O	Input/Output 5. Referenced to Vcсв
B4	16	14	14	I/O	Input/Output 4. Referenced to V _{CCB}
B3	17	15	15	I/O	Input/Output 3. Referenced to V _{CCB}
B2	18	16	16	I/O	Input/Output 2. Referenced to V _{CCB}
V _{CCB}	19	17	18	-	B-Port power supply
B1	20	18	17	I/O	Input/Output 1. Referenced to V _{ссв}

^{*}It is suggested to leave the unconnected pins floating.

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6 Voltage, Temperature, ESD and Thermal Ratings

6.1 Absolute Maximum Ratings(1)(2)(3)

Parameters		Min	Max	Unit
Supply voltage, V _{CCA}		-0.3	6.0	V
Supply voltage, V _{CCB}	Supply voltage, V _{CCB}			V
Input voltage range V	A port	-0.3	6.0	V
oltage range applied to any output in the high-impedance or power- state, Vo	B port	-0.3	6.0	V
Voltage range applied to any output in the high-impedance or power-off	A port	-0.3	6.0	V
state, Vo	B port	-0.3	6.0] v
Voltage range applied to any output in the high or low state. Ve	A port	-0.3	V _{CCA} +0.3	\ \
voltage range applied to any output in the high or low state, vo	Supply voltage, V _{CCB} Input voltage range,V _I d to any output in the high-impedance or power-off state, Vo plied to any output in the high or low state, Vo Input clamp current,I _{IK} Output clamp current,I _{OK} Continuous output current,I _O mus current through V _{CCA} ,V _{CCB} or GND Maximum junction temperature	-0.3	V _{CCA} +0.3	V
Input clamp current,I _{IK}	V_{I} <0		-50	mA
Output clamp current,loк	V ₀ <0		-50	mA
Continuous output current,Io			±50	mA
Continuous current through Vcca, VccB or GND			±100	mA
Maximum junction temperature			150	°C
Storage temperature range		-65	150	°C

⁽¹⁾Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

6.2 ESD Ratings

	E	Value	Unit	
V(ESD) E	Flacture static Disable and	Human-Body Model (HBM) ⁽¹⁾	±5K	V
	Electrostatic Discharge	Charged-Device Model (CDM) ⁽²⁾	±2K	V

⁽¹⁾ JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

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⁽²⁾ The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed

⁽³⁾The value of V_{CCA} and V_{CCB} are provided in the recommended operating conditions table

⁽²⁾ JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



6 Voltage, Temperature, ESD and Thermal Ratings(Continued)

6.3 Recommended Operating Conditions(3)

Vccı is the supply voltage associated with the input port. Vcco is the supply Voltage associated with the output port.

Parameter		Conditions		Тур	Max	Unit
		V _{CCA}			3.6	
Supply voltage ⁽¹⁾		V _{CCB}	2.3		5.5	V
	A-port I/Os	V _{CCA} =1.65 V to 1.95 V V _{CCB} =2.3 V to 5.5 V	V _{CCI} -0.2		V _{CCI}	
High-level input	A-port i/Os	V _{CCA} =2.3 V to 3.6 V V _{CCB} =2.3 V to 5.5 V	V _{CCI} -0.4		V _{CCI}	
voltage(V _{IH})	B-port I/Os	V _{CCA} =1.65 V to 3.6V V _{CCB} =2.3 V to 5.5 V	V _{CCI} -0.4		V _{CCI}	V
	OE input	V _{CCA} =1.65 V to 3.6 V V _{CCB} =2.3 V to 5.5 V	V _{CCI} ×0.8		5.5	
Low-level input	A-port I/Os	V _{CCA} =1.65 V to 1.95 V V _{CCB} =2.3 V to 5.5 V	0		0.15	V
voltage(VIL) ⁽²⁾	B-port I/Os	V _{CCA=} 1.65 V to 3.6 V V _{CCB} =2.3 V to 5.5 V	0		0.15	V
OE	OE input	V _{CCA} =1.65 V to 3.6 V V _{CCB} =2.3 V to 5.5 V	0		Vcca×0.25	V
Input transition rise	A-port I/0	Os push-pull driving			10	
Input transition rise or fall rate(Δt/Δv)	B-port I/0	Os push-pull driving			10	ns/V
Or fall fate(ΔVΔV)	Control input				10	
TA Operating free-air temperature		-	-40		85	°C

⁽¹⁾V_{CCA} must be less than or equal to V_{CCB}.

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⁽²⁾ The maximum V_{IL} value is provided to ensure that a valid V_{OL} is maintained. The V_{OL} value is V_{IL} plus the voltage drop across the pass gate transistor.



7 Electrical Specifications

7.1 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (1) (2) (3)

Pa	rameter	Conditions	Vcca	Vccв	Temp	Min	Тур	Max	Unit		
	Port A Output	I _{OH} =–20 μA					1 7 P	Wax			
V _{OHA}	High Voltage	$V_{IB} \ge V_{CCB} - 0.4V$	1.65V to 3.6V	2.3V to 5.5V	Full	V _{CCA} ×0.7			V		
V_{OLA}	Port A Output Low Voltage	I _{OL} =1mA V _{IB} ≤ 0.15 V	1.65V to 3.6V	2.3V to 5.5V	Full			0.3	V		
V _{OHB}	Port B Output High Voltage	I _{OH} =–20 μA V _{IA} ≥ V _{CCA} – 0.4V	1.65V to 3.6V	2.3V to 5.5V	Full	$V_{CCA} \times 0.7$			V		
V _{OLB}	Port B Output Low Voltage	$I_{OL}=1mA$ $V_{IA} \le 0.15 \text{ V}$	1.65V to 3.6V	2.3V to 5.5V	Full			0.3	V		
	Input				+25℃			±1			
lı	Leakage Current	OE	1.65V to 3.6V	2.3V to 5.5V	Full			±1.5	μA		
			0.4	0)// 5 5)/	+25℃			±0.5			
	Partial Power	A Ports	0V	0V to 5.5V	Full			±1			
l _{off}	Down Current	B.B. (0,44, 0,04	0.4	+25℃			±0.5	μΑ		
		B Ports	0V to 3.6V	0V	Full			±1			
	High-impedance	A or B port	4.05\/+- 2.0\/	2 2)/4- 5 5)/	+25℃			±0.5			
loz	State Output Current	OE=ÓV	OE=ÓV	OE=0V	1.65V to 3.6V	2.3V to 5.5V	Full			±1	μΑ
					1.65V to V _{CCB}	2.3v to 5.5V	Full			2.5	
Icca	V _{CCA} Supply Current	V₁=V _{O=} open I _O =0	3.6v	0V	Full			2.5	μΑ		
			0v	5.5V	Full			-1			
			1.65V to V _{CCB}	2.3v to 5.5V	Full			10			
Іссв	V _{CCB} Supply Current	V _{I=} V _O =open I _O =0	3.6v	0V	Full			-1	μΑ		
			0v	5.5V	Full			1			
I _{CCA} + I _{CCB}	Combined Supply Current	V _I =V _{CCI} or GND I _{O=} 0	1.65V to V _{CCB}	2.3v to 5.5V	Full			13	μΑ		
I _{CCZA}	V _{CCA} Supply Current	$V_{I}=V_{CCI}$ or $0V$ $I_{O}=0$, $OE=0V$	1.65V to V _{CCB}	2.3v to 5.5V	Full			1	μΑ		
I _{CCZB}	V _{CCB} Supply Current	$V_i=V_{CCI}$ or $0V$ $I_{O=}0$, $OE=0V$	2.3v to 3.6V	2.3v to 5.5V	Full			1	μΑ		
Ci	Input Capacitance	OE	3.3V	3.3V	+25℃		2.5		PF		
Cio	Input-to-output Internal	A Port	3.3V	3.3V	+25℃		5		PF		
O ₁₀	Capacitance	B Port	3.3V	3.3V	+25℃		5		FI		

⁽¹⁾ V_{CCI} is the V_{CC} associated with the input port.

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⁽²⁾ V_{CCO} is the V_{CC} associated with the output port

⁽³⁾ $V_{\text{\tiny CCA}}$ must be less than or equal to $V_{\text{\tiny CCB}}.$



7.2 Timing Requirements

$V_{CCA} = 1.8V \pm 0.15V$

		V _{CCB} =2.5V±0.2V	V _{CCB} =3.3V±0.2V	V _{CCB} =5V±0.2V	l lmi4
		Тур	Тур	Тур	Unit
Data Rate -	Push-pull Driving	21	22	24	Mhna
	Open-drain Driving	2	2	2	Mbps
Pulse	Push-pull Driving (Data Inputs)	47	45	41	
Duration(tw)	Open-drain Driving (Data Inputs)	500	500	500	ns

$V_{\text{CCA}}\text{=}2.5V\!\pm\!0.15V$

		V _{CCB} =2.5V±0.2V	V _{CCB} =3.3V±0.2V	V _{CCB} =5V±0.2V	l lmi4
		Тур	Тур	Тур	Unit
6 . 6 .	Push-pull Driving	20	22	24	Mhna
Data Rate	Open-drain Driving	2	2	2	Mbps
Pulse	Push-pull Driving (Data Inputs)	50	45	41	
Duration(tw)	Open-drain Driving (Data Inputs)	500	500	500	ns

V_{CCA} =3.3 $V\pm0.15V$

		V _{CCB} =3.3V±0.2V	V _{CCB} =5V±0.2V	l lmit
		Тур	Тур	Unit
Data Rate	Push-pull Driving	23	24	Mhna
	Open-drain Driving	2	2	Mbps
	Push-pull Driving (Data Inputs)	43	41	
Pulse Duration(tw)	Open-drain Driving (Data Inputs)	500	500	ns

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7.3 Switching Characteristics: V_{CCA} =1.8 $V\pm0.15V$

over recommended operating free-air temperature range (unless otherwise noted)

	Darameter		Conditions		V _{ccB} =3.3V±0.2V	V _{ccB} =5V±0.2V	11-14-	
	Parameter		Conditions		Тур	Тур	Units	
t _{PHL}	Propagation Delay Time	A to B	Push-pull Driving	5.6	5	5	ns	
TPHL	High-to-low Output	Alob	Open-drain Driving	7.5	7.9	8.3	113	
t _{РLН}	Propagation Delay Time	A to B	Push-pull Driving	10.0	9.5	9	ns	
IPLH	low-to-high Output	A to B	Open-drain Driving	181	170	154	115	
t _{РНL}	Propagation Delay Time	B to A	Push-pull Driving	7	7.1	7.2		
THE	High-to-low Output	BIOA	Open-drain Driving	7.6	8.1	9.2	ns	
t _{PLH}	Propagation Delay Time	B to A	Push-pull Driving	7.6	6.9	6	ns	
WLH .	low-to-high Output	DIO A	Open-drain Driving	163	145	118	113	
t _{en}	Enable Time	OE to A or B		135	159	182	ns	
t _{dis}	Disable Time		OE to A or B	170	174	181	ns	
t _{rA}	Input Rise Time	A port	Push-pull Driving	13.4	11.9	10.6	ns	
чA	input ruse rime	rise time	Open-drain Driving	68	66	62	113	
t _{rB}	Input Rise Time	B port	Push-pull Driving	13	12	11.6	ns	
чв	input ruse rime	rise time	Open-drain Driving	66	65	50	113	
4	Input Fall Time	A port fall	Push-pull Driving	5.6	4.7	4.0	no	
t _{fA}	Input Fall Time	Open-drain Driving	5.0	5.1	5.2	ns		
t _{fB}	Input Fall Time	B port fall	Push-pull Driving	3.0	3.0	2.9		
чв	input rail fille	time	Open-drain Driving	6.1	5.6	4.4	ns	
t _{sk(0)}	Skew(time), Output	Cha	annel-to-Channel Skew	0.5	0.5	0.5	ns	
Ma	ximum Data Rate		Push-pull Driving	22	23	24	Mbps	
ivia	Amani Bata Nato		Open-drain Driving		2	2	ivibps	

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7.4 Switching Characteristics, V_{CCA} =2.5 $V\pm0.15V$

over operating free-air temperature range (unless otherwise noted)

	_			V _{ccB} =2.5V±0.2V	V _{ccB} =3.3V±0.2V	V _{ccB} =5V±0.2V		
Parameter		Conditions		Тур	Тур	Тур	Units	
Propagation Delay Time		A to B	Push-pull Driving	3.5	3.5	3.2	ns	
t _{PHL}	High-to-low Output		Open-drain Driving	6.3	6.5	6.7		
	Propagation Delay Time		Push-pull Driving	4.5	4.9	4.7		
tрLН	low-to-high Output	A to B	Open-drain Driving	158	152	142	ns	
t _{PHL}	Propagation Delay Time	B to A	Push-pull Driving	3.7	3.9	4.6		
LPHL .	High-to-low Output	BIOA	Open-drain Driving	6	6.6	7.7	ns	
t _{PLH}	Propagation Delay Time	B to A	Push-pull Driving	4.8	4	2.5	ns	
ЧН	low-to-high Output		Open-drain Driving	153	138	116	115	
t _{en}	Enable Time	OE to A or B		7.7	41.8	130	ns	
t _{dis}	Disable Time	OE to A or B		175	181	182	ns	
t _{rA}	Input Rise Time	A port Rise Time	Push-pull Driving	9.8	8.6	7.5	ns	
4A	input Nise Time		Open-drain Driving	79	77	65		
	Innut Dies Time	B port	Push-pull Driving	9.8	8.7	8.1	ns	
t _{rB}	Input Rise Time	Rise Time	Open-drain Driving	93	68	53		
	Input Fall Time	A port Fall	Push-pull Driving	4.6	4.1	3.6	ns	
t _{fA}		Time	Open-drain Driving	5.1	5.1	5.2		
+_	Input Fall Time	B port Fall	Push-pull Driving	4.5	4.0	4.0	no	
t _{fB}		Time	Open-drain Driving	6.9	7.4	7.8	ns	
t _{sk(O)}	Skew(time), Output	Channel-to-Channel Skew		0.5	0.5	0.5	ns	
Ma	Maximum Data Rate		Push-pull Driving		24	24	Mbps	
Maximum Data Nate		Open-drain Driving		2	2	2		

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7.5 Switching Characteristics, $V_{CCA} = 3.3V \pm 0.3V$

over recommended operating free-air temperature range (unless otherwise noted)

Parameter			9		V _{ccB} =5V±0.2V		
			Conditions	TYP	TYP	Units	
	Propagation Delay Time t _{PHL} High-to-low Output		Push-pull Driving	2.1	2.2	ns	
ТРНL			Open-drain Driving	5.9	6.1		
	Propagation Delay Time		Push-pull Driving	1	3.3	- ns	
t _{PLH}	High-to-low Output	A to B	Open-drain Driving	138	131		
4	Propagation Delay Time	B to A	Push-pull Driving	2.3	2.6		
t _{PHL}	High-to-low Output	B to A	Open-drain Driving	5.4	6.6	ns	
t _{PLH}	Propagation delay time	B to A	Push-pull Driving	1.0	1.0	ns	
4-01	low-to-high Output	2 10 / 1	Open-drain Driving	133	115		
t _{en}	Enable Time		OE to A or B	4.7	5.2	ns	
t _{dis}	Disable Time		OE to A or B	174	182	ns	
t _{rA}	Input Rise Time	A port	Push-pull Driving	7.4	6.6	ne	
чA	input ruse rime	Rise Time	Open-drain Driving	75	67	ns	
t _{rB}	Input Rise Time	B port	Push-pull Driving	7.7	7.1		
lгВ	input Rise Time	Rise Time	Open-drain Driving 70		65	ns	
t	Input Fall Time	A port Fall Time	Push-pull Driving	3.4	3.0		
чA	t _{fA} Input Fall Time		Open-drain Driving	5.1 5.1		ns	
t _{fB}	Input Fall Time	B port Fall	Push-pull Driving	3.5	3.2	ns	
чь	Time		Open-drain Driving	6.8	6.7	110	
t _{sk(O)}	Skew(time), Output	Channel-to-Channel Skew		0.5	0.5	ns	
M	Maximum Data Rate		Push-pull Driving		24	Mbps	
Maximum Bata Nato			Open-drain Driving	2	2		

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8 Typical Characteristics

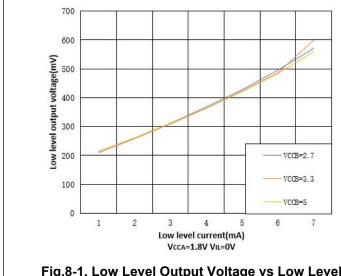


Fig.8-1. Low Level Output Voltage vs Low Level Current

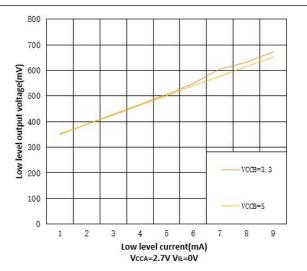


Fig.8-2. Low Level Output Voltage vs Low Level Current

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9 Parameter Measurement Information

Unless otherwise noted, all input pulsed are supplied by generators having the following characteristics:

- PSRR 10MHz
- Zo=50 Ω
- dv/dt ≥1V/ns

Note: All input pulses are measured one at a time with one transition per measurement

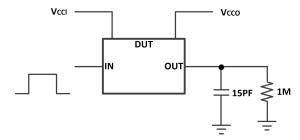


Fig.9-1. Data Rate, Pulse Duration, Propagation Delay, Output Rise and Fall Time Measurement Using a Push-Pull Driver

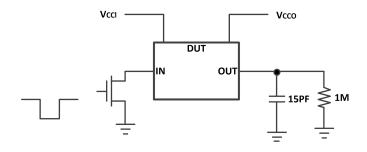


Fig.9-2. Data Rate, Pulse Duration, Propagation Delay, Output Rise and Fall Time Measurement Using an Open-Drain Driver

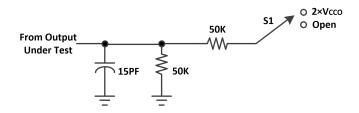


Fig.9-3. Load Circuit for Enable/Disable Time Measurement

Table 9-1 Switch Configuration for Enable/Disable Timing

Test	S1
t _{PZL} ⁽¹⁾ , t _{PLZ} ⁽²⁾	2×V _{cco}
t _{PHZL} ⁽¹⁾ , t _{PZH} ⁽²⁾	Open

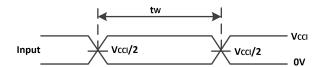
⁽¹⁾ t_{PZL} and t_{PZH} are the same as ten.

(2) t_{PLZ} and t_{PHZ} are the same as tdis.

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9 Parameter Measurement Information(Continued)



(1) All input pulses are measured one at a time, with one transition per measurement.

Fig.9-4. Voltage Waveforms Pulse Duration

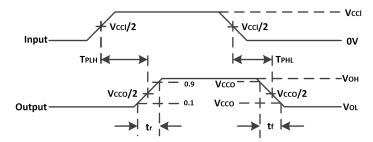


Fig.9-5. Voltage Waveforms Propagation Delay Times

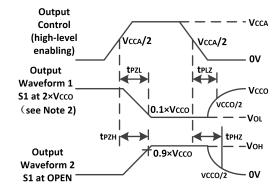


Fig.9-6. Voltage Waveforms Enable and Disable

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10 Detailed Description

10.1 Overview

The GT0108 IC is a Bi-direction voltage-level translator specifically designed for translating logic voltage levels. The A port can accept I/O voltages that cover from 1.65 V to 3.6 V range; The B port can accept I/O voltages from 2.3 V to 5.5 V. The device is a pass-gate architecture with edge-rate accelerators (one-shots) to improve the overall data rate. 10-k Ω pullup resistors that usually used in open-drain applications have been integrated inside IC with the advantage saving an external resistor. Not only the IC is designed for open-drain applications, but also this device can translate push-pull CMOS logic outputs.

10.2 Architecture

The GT0108 architecture (see Figure below) is a translator with Bi-direction-Sensing function that means a direction-control mechanism to control the direction of data flow from A to B or from B to A is not needed. These two bidirectional channels independently determine the direction of data flow without a direction-control signal. This auto-direction feature is realized by each I/O pin can be automatically reconfigured as either an input or an output.

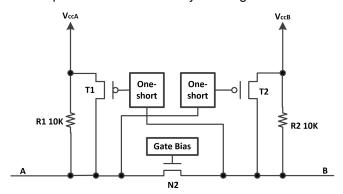


Fig.10-1. Architecture of GT0108

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11 Application Information

The GT0108 device can be used to bridge the digital-switching compatibility gap between two voltage nodes to successfully interface logic threshold levels found in electronic systems. It should be used in a point-to-point topology for interfacing devices or systems operating at different interface voltages with one another. Its primary target application use is for interfacing with open-drain drivers on the data I/Os such as I2C or 1-wire, where the data is bidirectional and no control signal is available. The device can also be used in applications where a push-pull driver is connected to the data I/Os, but the GT0108 might be a better option for such push-pull applications.

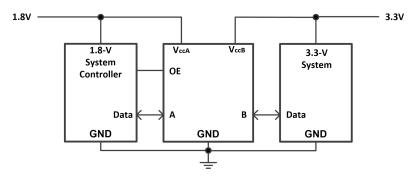


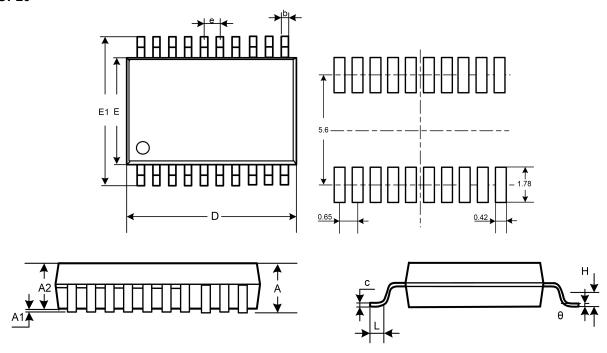
Fig.11-1. Typical Application Schematic

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12 Package Outline Dimension

TSSOP20



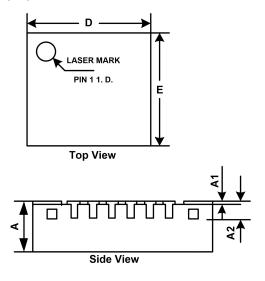
Symbol	Dimension	s In Millimeters	Dimensions In Inches			
Symbol	Min	Max	Min	Max		
Α		1.200		0.047		
A1	0.050	0.150	0.002	0.006		
A2	0.800	1.050	0.031	0.041		
b	0.200	0.280	0.008	0.011		
С	0.130	0.170	0.005	0.007		
D	6.400	6.600	0.252	0.260		
E	4.300	4.500	0.169	0.177		
E1	E1 6.200		6.600 0.244			
е	0.0	65BSC	0.0	26BSC		
L	0.450	0.750	0.018	0.030		
Н	0.2	25TYP	0.01TYP			
θ	0°	8°	0°	8°		

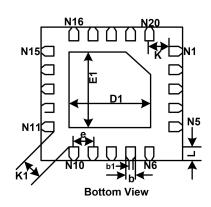
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12 Package Outline Dimension(Continued)

QFN3×3-20L



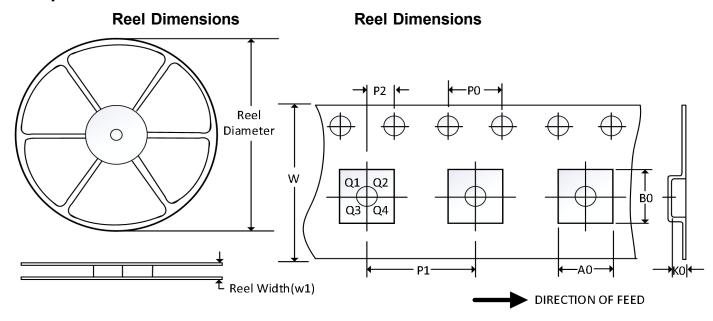


Comple al	Dimensions	In Millimeters	Dimensions In Inches			
Symbol	Min	Max	Min	Max		
A	0.700	0.800	0.028	0.031		
A1	0.000	0.050	0.000	0.002		
A2	0.203REF 0.0			08REF		
D	2.950	3.050	0.116	0.120		
Е	2.950	3.050	0.116	0.120		
D1	1.550	1.650	0.061	0.065		
E1	1.550	1.650	0.061	0.065		
K	0.30	00REF	0.012REF			
K1	0.40	00REF	0.016REF			
b	0.150	0.250	0.006	0.010		
b1	0.15	50REF	0.006REF			
е	0.40	00BSC	0.016BSC			
L	0.350	0.450	0.014	0.018		

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13 Tape and Reel Information



Note: The picture is only for reference. Please make the object as the standard.

Key Parameter List of Tape and Reel

Package type	Reel diameter	Reel width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 QµAdrant
TSSOP20	13"	12.4	6.75	6.95	1.20	4.0	8.0	2.0	12.0	Q1
QFN3X3-20L	13"	12.4	3.35	3.35	1.13	4.0	8.0	2.0	12.0	Q1

(1)All dimensions are nominal. (2)Plastic or metal protrusions of 0.15mm maximum per side are not included.

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